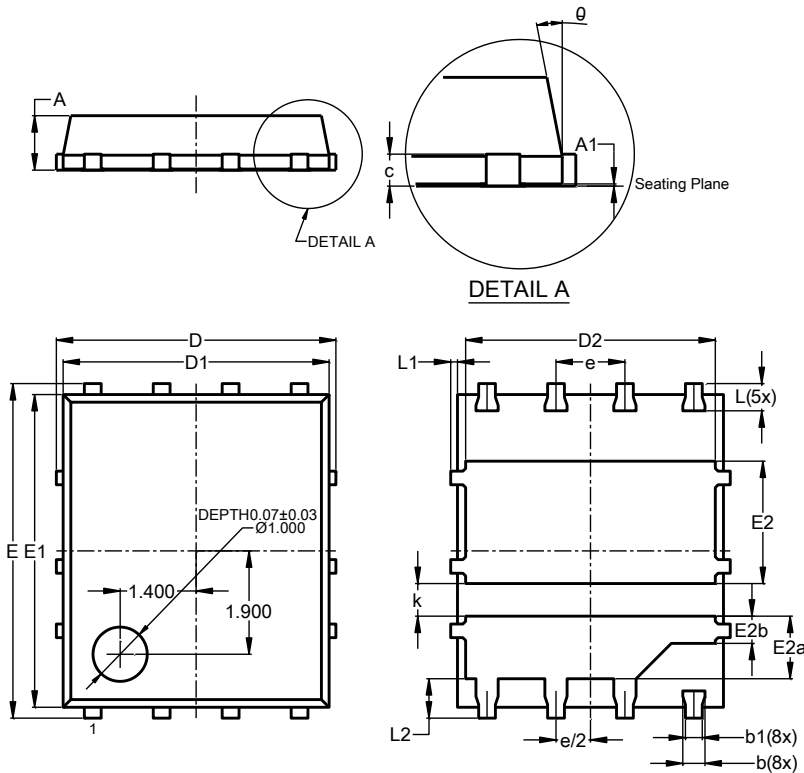


Package Outline Dimensions

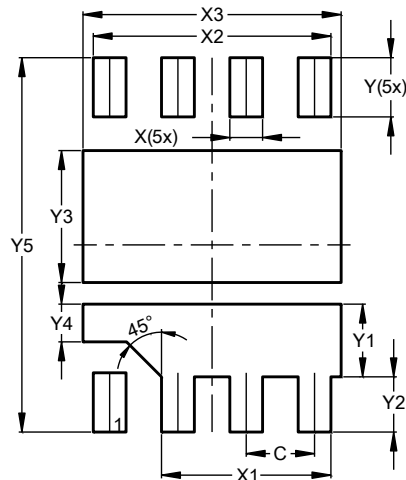
PowerDI5060-8 (Type S)



PowerDI5060-8 (Type S)			
Dim	Min	Max	Typ
A	0.90	1.10	1.00
A1	0.00	0.05	--
b	0.33	0.46	0.41
b1	0.23	0.36	0.31
c	0.230	0.330	0.254
D	--	--	5.15
D1	4.70	5.10	4.90
D2	4.50	4.70	4.60
E	--	--	6.15
E1	5.55	5.95	5.75
E2	2.15	2.35	2.25
E2a	1.05	1.25	1.15
E2b	0.45	0.55	0.50
e	1.27BSC		
k	0.50	0.70	0.60
L	0.40	0.60	0.50
L1	0.00	0.20	0.125
L2	0.625	0.825	0.725
θ	10°	12°	11°
All Dimensions in mm			

Suggested Pad Layout

PowerDI5060-8 (Type S)



Dimensions	Value (in mm)
C	1.270
X	0.610
X1	3.150
X2	4.420
X3	4.800
Y	1.100
Y1	1.350
Y2	1.025
Y3	2.450
Y4	0.700
Y5	6.950

ALL DIMENSIONS ARE NOMINAL VALUES SHOWN IN MILLIMETERS

Note: The suggested land pattern dimensions have been provided for reference only, as actual pad layouts may vary depending on application. These numbers may be modified based on user equipment capability or fabrication criteria. A more robust pattern may be desired for wave soldering and is calculated by adding 0.2 mm to the 'Z' dimension. For further information, please reference document IPC-7351A, Naming Convention for Standard SMT Land Patterns, and for International grid details, please see document IEC, Publication 97.